



Vacuum, Gas and Plasma Programmable Process Ovens  
(temperature up to 1100°C), RTP, Reflow Soldering



Monolayer Deposition Equipment  
ALD Atomic Layer Deposition  
Aerosol Coatings



Precision Temperature Forcing Systems for components  
and assemblies ranging from -100°C to +225°C



Ultrasonic Precision Spray Coating Systems



Spinners for: coating, developing and cleaning  
+ associated dispensers



Semiconductor Package Decapsulation  
Chemical, Laser



Semiconductor Package (backside opening)  
Advanced Sample Preparation Equipment:  
grinding, polishing, lapping and sawing



Nordson MARCH is the global leader in advanced  
plasma machine technology for Multiple Manufacturing  
Industries



Nitriding Systems



**SEGEN**  
TECHNOLOGIES LTD.

"Service & Solutions in another Dimension"



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Segen Technologies LTD.  
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Segen Technologies LTD. represents the leading  
industries at the high-tech manufacturing sector.

We provide our customers with pre-sales support,  
offering the best machine or tools suitable for  
their application.

Our after sales such as installation and maintenance  
services are designed to give customers  
the confidence to operate and achieve the  
maximum performance.

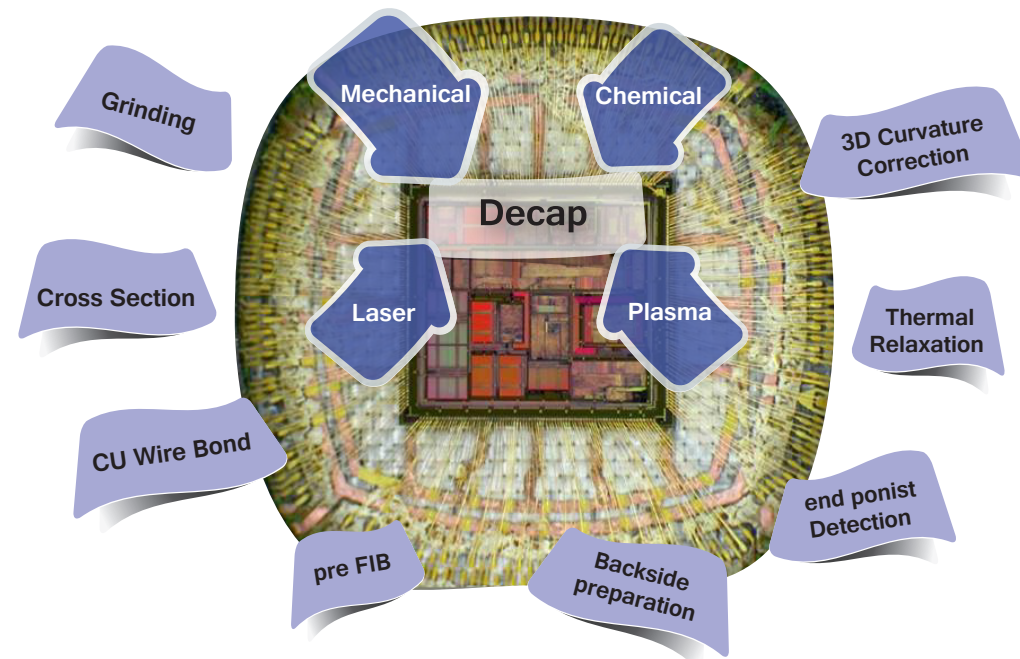
Therefore our slogan is —

**"Service & Solutions in another Dimension"**

## Failure analysis Sample preparation and Decapsulation

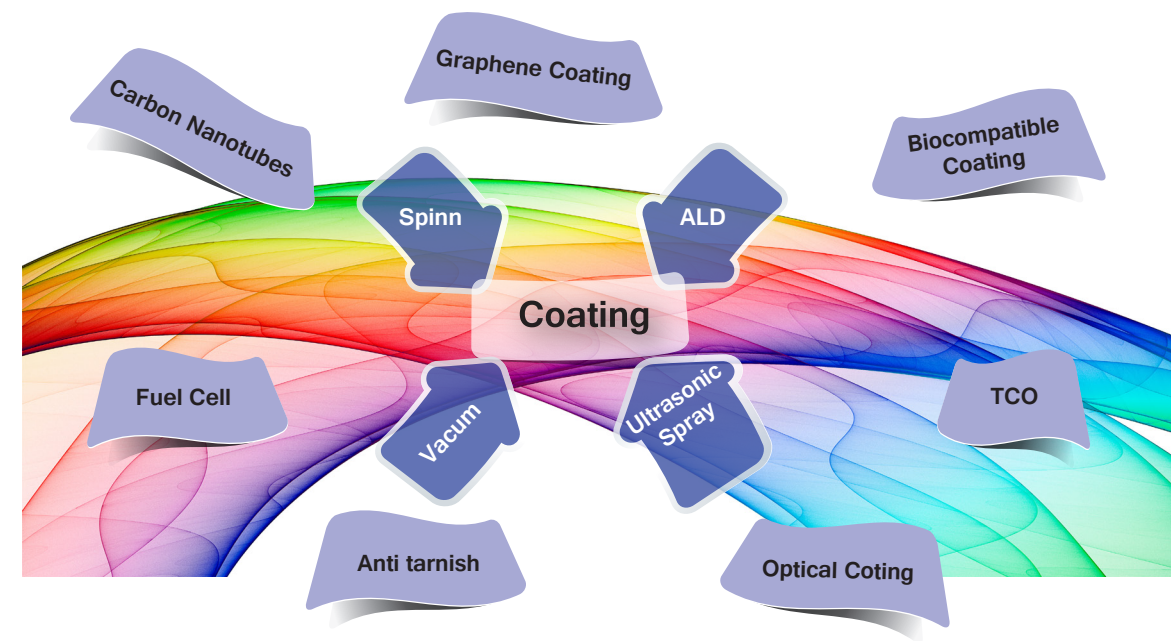
Discover what went wrong with your chips or material, and identify counterfeit components:

Exposure of bond wires, incl. copper & die surface  
Front + Backside opening & chip thinning and polishing  
Chip delayering, incl. 3-D curvature correction  
Dicing, sawing, cross-sectioning, grinding, & polishing



## Coating

From angstrom- through nano and micro thicknesses  
Offers excellent uniformity, Pinhole-free, Supports super-high aspect ratios of 1000:1 and Saves coating material.  
Suitable for thicker conductive & non-conductive materials for flat surfaces, 3-dimensional and even powders



## Process

Equipment for a broad range of processes like:  
Precise Thermal Profiling - Process in Vacuum Oven  
Plasma surface preparation to promote adhesion and better wire bonding  
Hermetic component sealing, incl. getters  
Thermal Temperature Forcing: Burn-in, Cycling, Shock, HAST  
Voidless reflow soldering & brazing  
Inert atmosphere high-temperature vacuum processing  
Metal surface hardening by plasma nitriding

